



 MICROCHIP						Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3				
Semiconductor Device Type: EKE / TV (W9X) 048 TSOP 12x20mm Matte Tin																
Basic Substance		CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	377.31	(mg) Total	Mold Compound	% of Total Weight	66.84					
Silica, vitreous (or fused)		60676-86-0	Mold Compound	56.814	320.715	568,140		Silica, vitreous (or fused)	60676-86-0	85.00						
Epoxy Resin		Trade Secret	Mold Compound	5.815	32.826	58,151			Epoxy Resin	Trade Secret			8.70			
Phenolic Resin		Trade Secret	Mold Compound	4.010	22.639	40,104			Phenolic Resin	Trade Secret			6.00			
Carbon Black		1333-86-4	Mold Compound	0.201	1.132	2,005			Carbon Black	1333-86-4			0.30			
Total						100.00										
Copper		7440-50-8	Lead Frame	26.982	152.312	269,818	159.92	(mg) Total	Lead Frame	% of Total Weight	28.33					
Nickel		7440-02-0	Lead Frame	0.720	4.062	7,196			Copper	7440-50-8			95.24			
Silicon		7440-21-3	Lead Frame	0.127	0.720	1,275			Nickel	7440-02-0			2.54			
Magnesium		7439-95-4	Lead Frame	0.028	0.160	283			Silicon	7440-21-3			0.45			
Silver		7440-22-4	Lead Frame	0.473	2.669	4,728			Magnesium	7439-95-4			0.10			
Silver		7440-22-4	Die Attach	0.304	1.716	3,040		(mg) Total	Die Attach	% of Total Weight	0.38					
Epoxy Resin		Trade Secret	Die Attach	0.065	0.365	646			Silver	7440-22-4			1.67			
Copper		7440-50-8	Die Attach	0.011	0.064	114			Total				100.00			
Silicon		7440-21-3	Chip (Die)	1.380	7.790	13,800			2.15	(mg) Total			Die Attach	% of Total Weight	0.38	
Doped Gold		7440-57-5	Wire Bond	0.320	1.806	3,200				Silver			7440-22-4	80.00		
Tin		7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	2.750	15.524	27,500	Epoxy Resin	Trade Secret			17.00					
TOTALS:			100.000	564.500	1,000,000	Copper	7440-50-8	3.00								
0.5645 g Total Mass																
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)																
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.																
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.																
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/																
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.																
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.																
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.																
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.																
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table																
							7.79	(mg) Total	Chip (Die)	% of Total Weight	1.38					
								Silicon	7440-21-3	100.00						
									Total	100.00						
							1.81	(mg) Total	Wire Bond	% of Total Weight	0.32					
								Doped Gold	7440-57-5	100.00						
									Total	100.00						
							15.52	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	2.75					
								Tin	7440-31-5	100.00						
									Total	100.00						
							564.500									
							100.000									